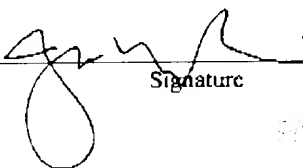


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/627,979 Examiner: DiLinh Nguyen
Inventor: Randy H. Y. Lo, Chi-Chuan Wu and Ssu-Cheng Lai
Filed: June 24, 2000 Art Unit: 2814
Title: Method Of Packaging Multi Chip Module

Certificate of Transmission under 37 CFR 1.8

I hereby certify that this correspondence (total / 8 pages) is being facsimile transmitted to the Patent and Trademark Office (Fax No. 703-872-9318) on Feb 27, 2002


Signature

Commissioner for Patents
Washington, D.C. 20231

Sir:

AMENDMENT A

In response to the Office Action mailed 12/03/2001, please amend the above-identified application as follows:

SPECIFICATION:

Page 1, lines 4-8, amend the paragraph as:

The present invention relates to a method of packaging an integrated circuit (IC) package, and particularly, to a low cost and high reliability method of packaging a plurality of bare chips and CSP (Chip Scale Package) on a substrate for a multi chip module package (MCM package) so as to increase the package density.

Page 1, lines 11-16, amend the paragraph as: